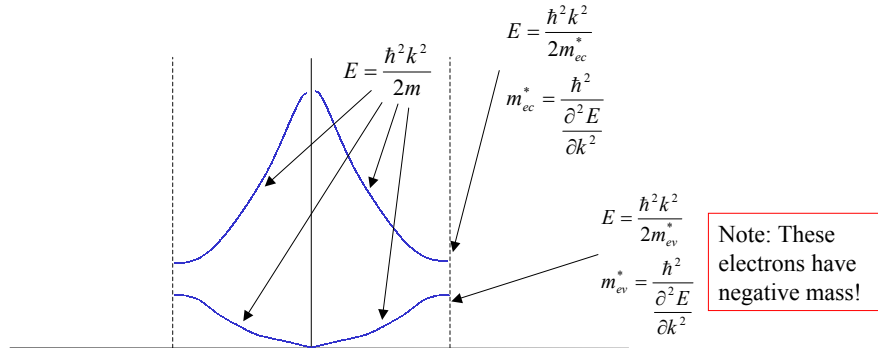


Properties of non-free electrons

- Electrons near the diffraction condition are not approximated as free
- Their properties can still be viewed as free e- if an 'effective mass' m^* is used



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Band Gap Energy Trends

IV / III-V / II-VI*

II B	III	IV	V	VI
	B	C	N	O
	Al	Si	P	S
Zn	Ga	Ge	As	Se
Cd	In	Sn	Sb	Te

MP (°K)	Eg (eV)	a ₀ Å
	6 / 10	3.56 / 3.16
1685 / 1770	1.1 / 3	5.42 / 5.46
1231 / 1510 / ?	0.72 / 1.35 / ?	5.66 / 5.65 / ?
508 / 798 / ?	0.08 / 0.18 / 1.45	6.45 / 6.09 / ?

* Fill in as many of the question marks as you can.

Note Trends:

1. As descend column, MP decreases as does Eg while a₀ increases.
2. As move from IV to III-V to II-VI compounds become more ionic, MP and Eg increase while a₀ tends to decrease



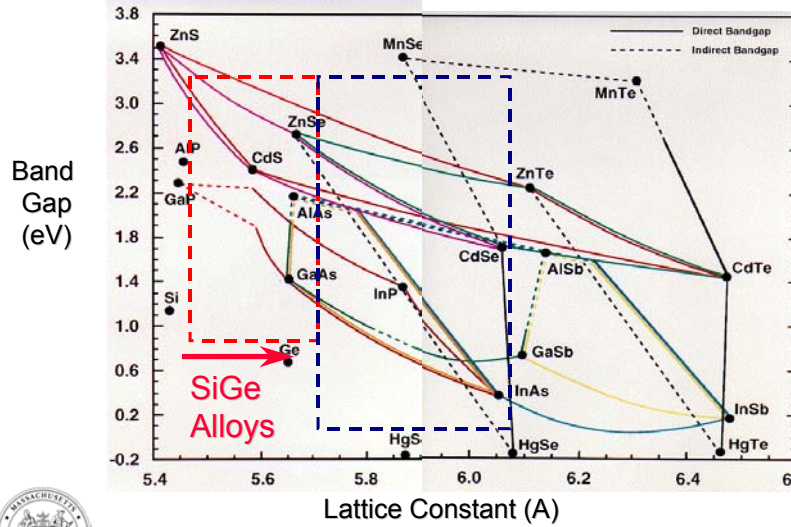
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Trends in III-V and II-VI Compounds

➔ Larger atoms, weaker bonds, smaller U , smaller E_g , higher μ , more costly!



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Energy Gap and Mobility Trends

Material	$E_g(\text{eV})^\circ\text{K}$	$\mu(\text{cm}^2/\text{V}\cdot\text{s})$
GaN	3.39	150
AlAs	2.3	180
GaP	2.4	2,100
GaAs	1.53	16,000
InP	1.41	44,000
InAs	0.43	120,000
InSb	0.23	1,000,000

Remember that: $\mu = \frac{e\tau}{m^*}$ and $\frac{1}{m^*} = \frac{1}{\hbar^2} \frac{\partial^2 E}{\partial k^2}$



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Metals and Insulators



- E_F in mid-band area: free e-, *metallic*
- E_F near band edge
 - E_F in or near kT of band edge: *semimetal*
 - E_F in gap: *semiconductor*
- E_F in very large gap, *insulator*



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Semiconductors



- Intermediate magnitude band gap enables free carrier generation by three mechanisms
 - photon absorption
 - thermal
 - impurity (i.e. doping)
- Carriers that make it to the next band are free carrier- like with mass, m^*



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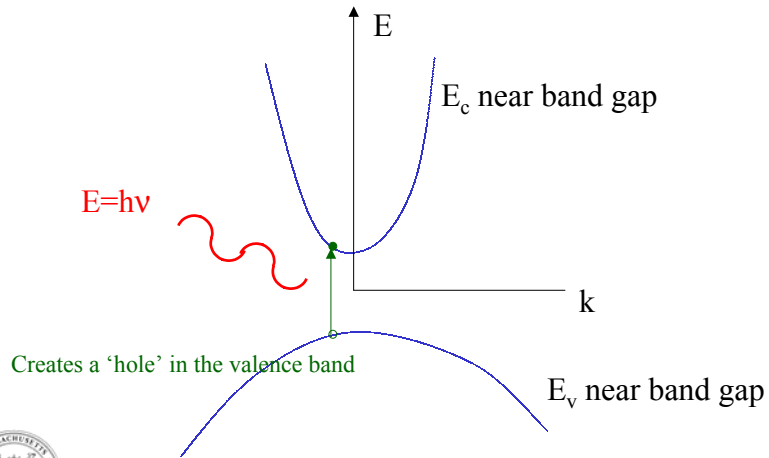
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Semiconductors: Photon Absorption



- When $E_{\text{light}} = h\nu > E_g$, an electron can be promoted from the valence band to the conduction band



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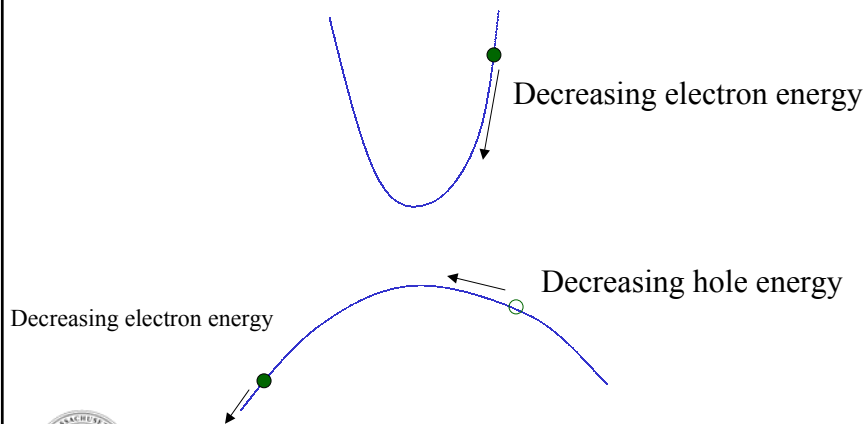
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Holes and Electrons



- Instead of tracking electrons in valence band, more convenient to track missing electrons, or 'holes'
- Also removes problem with negative electron mass: since hole energy increases as holes 'sink', the mass of the hole is positive as long as it has a positive charge



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Conductivity of Semiconductors

- Need to include both electrons and holes in the conductivity expression

$$\sigma = ne\mu_e + pe\mu_h = \frac{ne^2\tau_e}{m_e^*} + \frac{pe^2\tau_h}{m_h^*}$$

p is analogous to n for holes, and so are τ and m^*

Note that in both photon stimulated promotion as well as thermal promotion, an equal number of holes and electrons are produced, i.e. $n=p$



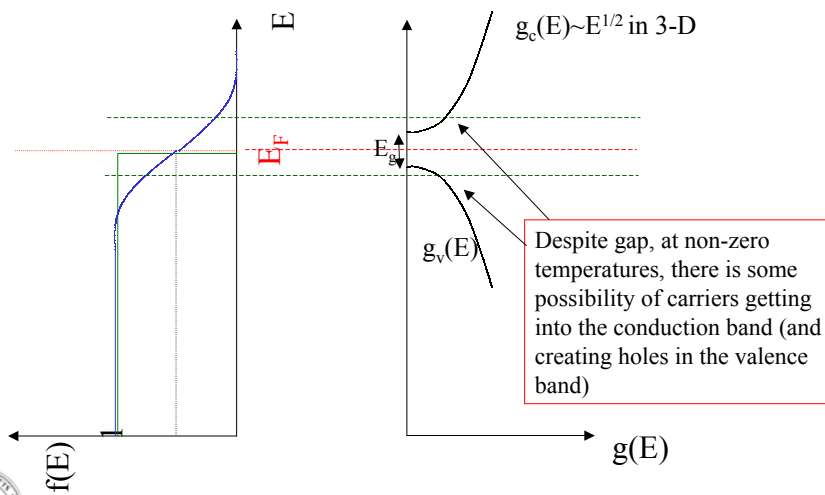
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Thermal Promotion of Carriers

- We have already developed how electrons are promoted in energy with T: Fermi-Dirac distribution
- Just need to fold this into picture with a band-gap



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Density of Thermally Promoted of Carriers

Number of electrons per
volume in conduction
band

$$n = \int_{E_c}^{\infty} f(E) g(E) dE$$



Density of electron states per volume per dE

Fraction of states occupied at a particular temperature

$$f(E) = \frac{1}{e^{\frac{E-E_F}{k_b T}} + 1} \approx e^{-\frac{E-E_F}{k_b T}} \quad \text{when } (E-E_F) \gg k_b T$$

$$g_c(E) = \frac{1}{2\pi^2} \left(\frac{2m_e^*}{\hbar^2} \right)^{\frac{3}{2}} (E-E_g)^{\frac{1}{2}} \longrightarrow n = \frac{1}{2\pi^2} \left(\frac{2m_e^*}{\hbar^2} \right)^{\frac{3}{2}} e^{\frac{E_F}{k_b T}} \int_{E_g}^{\infty} (E-E_g)^{\frac{1}{2}} e^{-\frac{E}{k_b T}} dE$$

Since $\int_0^{\infty} x^2 e^{-x} dx = \frac{\sqrt{\pi}}{2}$, then $n = 2 \left(\frac{m_e^* k_b T}{2\pi \hbar^2} \right)^{\frac{3}{2}} e^{\frac{E_F}{k_b T}} e^{-\frac{E_g}{k_b T}}$

$$n = N_c e^{-\frac{E_g - E_F}{k_b T}}$$



Density of Thermally Promoted of Carriers

- A similar derivation can be done for holes, except the density of states for holes is used
- Even though we know that n=p, we will derive a separate expression anyway since it will be useful in deriving other expressions

$$g_v(E) = \frac{1}{2\pi^2} \left(\frac{2m_h^*}{\hbar^2} \right)^{\frac{3}{2}} (-E)^{\frac{1}{2}} \longrightarrow p = \int_{-\infty}^0 f_h(E) g_v(E) dE, \quad \text{where } f_h = 1 - f(E)$$

$$p = 2 \left(\frac{m_h^* k_b T}{2\pi \hbar^2} \right)^{\frac{3}{2}} e^{-\frac{E_F}{k_b T}}$$

$$p = N_v e^{-\frac{E_F}{k_b T}}$$



Thermal Promotion



- Because electron-hole pairs are generated, the Fermi level is approximately in the middle of the band gap
- The law of mass action describes the electron and hole populations, since the total number of electron states is fixed in the system

$$n = p \text{ gives } E_F = \frac{E_g}{2} + \frac{3}{4} k_b T \ln \left(\frac{m_h^*}{m_e^*} \right)$$

Since m_e^* and m_h^* are close and in the ln term, the Fermi level sits about in the center of the band gap

$$p \text{ or } n = n_i = 2 \left(\frac{k_b T}{2\pi\hbar^2} \right)^{\frac{3}{2}} (m_e^* m_h^*)^{\frac{3}{2}} e^{\frac{-E_g}{2k_b T}}$$

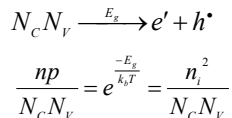


Law of Mass Action for Carrier Promotion



$$n_i^2 = np = 4 \left(\frac{k_b T}{2\pi\hbar^2} \right)^3 (m_e^* m_h^*)^{\frac{3}{2}} e^{\frac{-E_g}{k_b T}} ; \quad n_i^2 = N_C N_V e^{\frac{-E_g}{k_b T}}$$

- Note that re-arranging the right equation leads to an expression similar to a chemical reaction, where E_g is the barrier.
- $N_C N_V$ is the density of the reactants, and n and p are the products.



- Thus, a method of changing the electron or hole population without increasing the population of the other carrier will lead to a dominant carrier type in the material.
- Photon absorption and thermal excitation produce only pairs of carriers: *intrinsic semiconductor*.
- Increasing one carrier concentration without the other can only be achieved with impurities, also called doping: *extrinsic semiconductors*.



Intrinsic Semiconductors

- Conductivity at any temperature is determined mostly by the size of the band gap
- All intrinsic semiconductors are insulating at very low temperatures

Recall:
$$\sigma = ne\mu_e + pe\mu_h = \frac{ne^2\tau_e}{m_e^*} + \frac{pe^2\tau_h}{m_h^*}$$

$$\sigma_{\text{int}} = n_i e (\mu_e + \mu_h) \propto e^{\frac{-E_g}{2k_b T}}$$
 ← This can be a measurement for E_g

For Si, $E_g=1.1\text{eV}$, and let μ_e and μ_h be approximately equal at $1000\text{cm}^2/\text{V}\cdot\text{sec}$ (very good Si!).
 $\sigma \sim 10^{10}\text{cm}^{-3} * 1.602 \times 10^{-19} * 1000\text{cm}^2/\text{V}\cdot\text{sec} = 1.6 \times 10^{-6}\text{ S/m}$, or a resistivity ρ of about $10^6\text{ ohm}\cdot\text{m}$ max.

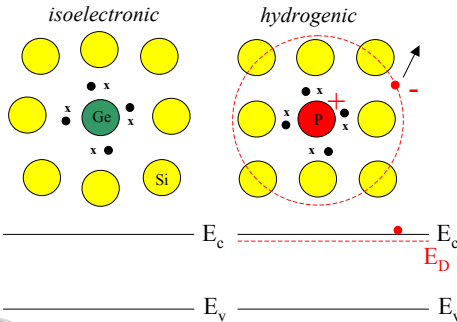
- One important note: No matter how pure Si is, the material will always be a poor insulator at room T.
- As more analog wireless applications are brought on Si, this is a major issue for system-on-chip applications.



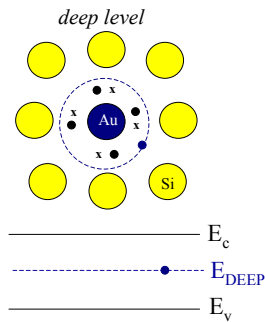
Extrinsic Semiconductors

- Adding ‘correct’ impurities can lead to controlled domination of one carrier type
 - n-type is dominated by electrons
 - p-type if dominated by holes
- Adding other impurities can degrade electrical properties

Impurities with close electronic structure to host



Impurities with very different electronic structure to host



Hydrogenic Model

- For hydrogenic donors or acceptors, we can think of the electron or hole, respectively, as an orbiting electron around a net fixed charge
- We can estimate the energy to free the carrier into the conduction band or valence band by using a modified expression for the energy of an electron in the H atom

$$E_n = \frac{me^4}{8\epsilon_0^2 h^2 n^2} = -\frac{13.6}{n^2} \text{ (in eV)}$$

$$E_n = \frac{me^4}{8\epsilon_0^2 h^2 n^2} \xrightarrow{\frac{e^2}{\epsilon_r} = e^2} \frac{m^* e^4}{8\epsilon_0^2 h^2 n^2 \epsilon_r^2} = -\frac{13.6}{n^2} \frac{m^*}{m} \frac{1}{\epsilon_r^2}$$

- Thus, for the ground state $n=1$, we can see already that since ϵ is on the order of 10, the binding energy of the carrier to the center is $<0.1\text{eV}$
- Expect that many carriers are then thermalize at room T
- Experiment:
 - B acceptor in Si: .046 eV
 - P donor in Si: 0.044 eV
 - As donor in Si: 0.049



The Power of Doping

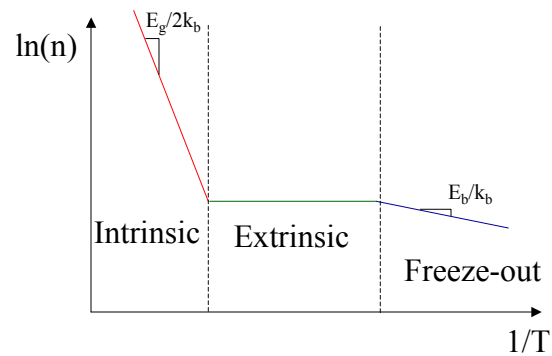
- Can make the material n-type or p-type: Hydrogenic impurities are nearly fully ionized at room temperature
 - n_i^2 for Si: $\sim 10^{20}\text{cm}^{-3}$
 - Add 10^{18}cm^{-3} donors to Si: $n \sim N_d$
 - $n \sim 10^{18}\text{cm}^{-3}$, $p \sim 10^2$ (n_i^2/N_d)
- Can change conductivity drastically
 - 1 part in 10^7 impurity in a crystal ($\sim 10^{22}\text{cm}^{-3}$ atom density)
 - $10^{22} * 1/10^7 = 10^{15}$ dopant atoms per cm^{-3}
 - $n \sim 10^{15}$, $p \sim 10^{20}/10^{15} \sim 10^5$
 - $\sigma/\sigma_i \sim (p+n)/2n_i \sim n/2n_i \sim 10^5!$

Impurities at the ppm level drastically change the conductivity
(5-6 orders of magnitude)



Expected Temperature Behavior of Doped Material (Example:n-type)

- 3 temperature regimes



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Contrasting Semiconductor and Metal Conductivity

$$\sigma = \frac{ne^2\tau}{m}$$

- Semiconductors
 - changes in $n(T)$ can dominate over τ
 - as T increases, conductivity increases
- Metals
 - n fixed
 - as T increases, τ decreases, and conductivity decreases



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General Interpretation of τ



- Metals and majority carriers in semiconductors
 - τ is the scattering length
 - Phonons (lattice vibrations), impurities, dislocations, and grain boundaries can decrease τ

$$\frac{1}{\tau} = \frac{1}{\tau_{phonon}} + \frac{1}{\tau_{impur}} + \frac{1}{\tau_{disl}} + \frac{1}{\tau_{gb}} + \dots$$

$$\tau_i = \frac{l_i}{v_{th}} = \frac{1}{v_{th}\sigma_i N_i} \quad \text{where } \sigma \text{ is the cross-section of the scatterer, } N \text{ is the number of scatterers per volume, and } l \text{ is the average distance before collisions}$$

$$l_i \sigma_i N_i = 1$$

The mechanism that will tend to dominate the scattering will be the mechanism with the shortest l (most numerous), unless there is a large difference in the cross-sections

Example: Si transistor, τ_{phonon} dominates even though τ_{impur} gets worse with scaling.



Estimate of T dependence of conductivity

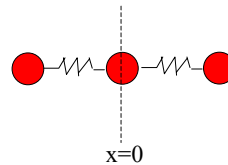


- $\tau \sim l$ for metals
- $\tau \sim 1/v_{th}$ for semiconductors
- First need to estimate $l = 1/N\sigma$

$$l_{ph} = \frac{1}{N_{ion}\sigma_{ion}}$$

$$\sigma_{ion} \propto \pi \langle x^2 \rangle$$

$$\langle x^2 \rangle = \frac{\int_{-\infty}^{+\infty} \Psi^* x^2 \Psi dx}{\int_{-\infty}^{+\infty} \Psi^* \Psi dx}$$



Use Ψ for harmonic oscillator, get:

$$k \langle x^2 \rangle = \langle E \rangle = \frac{\hbar\omega}{e^{\hbar\omega/kT} - 1}$$

Average energy of harmonic oscillator



Estimate of T dependence of conductivity

$$k\langle x^2 \rangle = \langle E \rangle = \frac{\hbar\omega}{e^{kT} - 1}$$

$$\hbar\omega = k\theta$$

$$\langle E \rangle = \frac{k\theta}{e^{\frac{\theta}{T}} - 1}$$

Therefore, $\langle x^2 \rangle$ is proportional to T if T large compared to θ :

$$e^{\frac{\theta}{T}} \approx 1 + \frac{\theta}{T}$$

$$\langle x^2 \rangle \propto T$$

$$l \propto \frac{1}{\sigma} \propto \frac{1}{\langle x^2 \rangle} \propto \frac{1}{T}$$

For a metal:
$$\sigma_{cond} \propto \mu \propto \tau \approx \frac{l}{v_F} = \frac{1}{v_F N_{ion} \pi \langle x^2 \rangle} = \frac{1}{v_F N_{ion} \pi T}$$

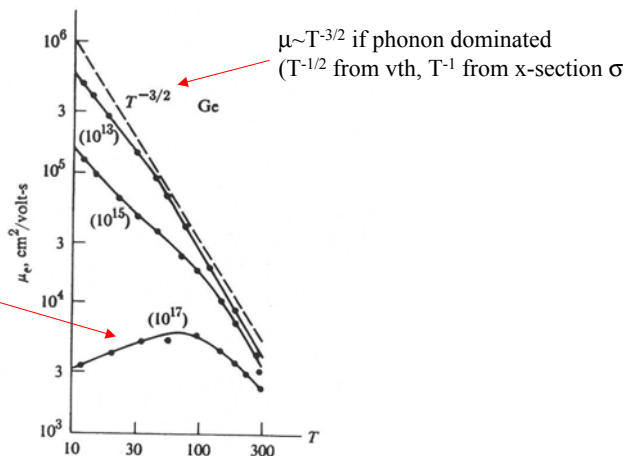
For a semiconductor, remember that the carriers at the band edges are classical-like:

$$\tau = \frac{l}{v_{th}} = \frac{l}{\sqrt{\frac{3kT}{m^*}}} \propto \frac{l}{T^{1/2}} \propto T^{-3/2}$$

$$\mu = \frac{e\tau}{m^*} \propto T^{-3/2}$$



Example: Electron Mobility in Ge



At higher doping, the ionized donors are the dominate scattering mechanism

